Product End-of-Life Disassembly Instructions

Product Category: Notebooks

Marketing Name / Model
[List multiple models if applicable.]

HP Stream 11 Pro G5 Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td></td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with</td>
<td>Battery(ies) are attached to the product by (check all that apply with an</td>
<td>1</td>
</tr>
<tr>
<td>the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>“x” inside the “[ ]”): [x] screws [x] snaps [0] adhesive [0] other. Explain _____</td>
<td></td>
</tr>
<tr>
<td></td>
<td>NOTE: Add detailed removal procedures including required tools in the</td>
<td></td>
</tr>
<tr>
<td></td>
<td>sections 3.1 and 3.2</td>
<td></td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps,</td>
<td>0</td>
</tr>
<tr>
<td></td>
<td>switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter</td>
<td></td>
<td></td>
</tr>
<tr>
<td>or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) |  |  
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. |  
Components and waste containing asbestos |  |  
Components, parts and materials containing refractory ceramic fibers |  |  
Components, parts and materials containing radioactive substances |  |  

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

### Tool Description | Tool Size (if applicable)
--- | ---
Screw driver | #0, #1

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove Rubber foot X4 from D base
2. Remove C top sub-Assy from unit
3. Remove TP support bracket & TP module from C top sub-Assy
4. Remove Bezel & panel & Cover from LCD sub-Assy
5. Remove camera module & camera cable & LVDS cable & antenna cable
6. Remove L/R hinge
7. Remove speaker module
8. Remove Battery
9. Remove FFC
10. Remove Thermal module
11. Remove D/B & M/B & WLAN card
12. Remove DC-IN Cable

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Total part disassembly
2 Remove Rubber and Screw

3 Remove TOP Assy

4 Remove TP support bracket & TP module
5 Remove Bezel & panel & Cover from LCD sub-Assy

6 Remove camera module & camera cable & LVDS cable & antenna cable

7 Remove L/R hinge
8 Remove speaker module

9 Remove Battery

10 Remove FFC

11 Remove Thermal module
12 Remove D/B & M/B & WLAN card

13 Remove DC-IN Cable